

**IN THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. – 15. (canceled)

16. (original) A method, comprising:

applying thermally conductive material to a first side of a layer, the layer having a connection pad on the first side of the layer, a via extending from the first side to a second side of the layer, and a conductive trace between the via and the connection pad on the first side of the layer, the thermally conductive material being applied to be in contact with at least one of the via and the conductive trace;

connecting a first component to the connection pad with a first connection material having a melting point; and

connecting, after connecting the first component, a second component to a second side of the layer after connecting the first component to the connection pad, wherein the second component is connected to the second side with a second connection material raised to a temperature at least as high as the melting point of the first connection material.

17. (original) The method of claim 16, wherein:

the connection pad comprises a ball grid array pad; and

the first connection material comprises solder.

18. (original) The method of claim 17, further comprising applying solder paste to the ball grid array pad before applying the thermally conductive material to the first side of a structural layer.

19. (original) The method of claim 17, wherein the second component is connected to the second side of the structural layer by a wave solder process.

20. (original) The method of claim 16, wherein the thermally conductive material comprises a thermal epoxy.

21. – 27. (canceled)